

SMD Comm COG Flex, Ceramic, 680 pF, 5%, 250 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 0603



Dimensions

| Dimensions | |
|------------|------------------|
| Chip Size | 0603 |
| L | 1.6mm +/-0.17mm |
| W | 0.8mm +/-0.15mm |
| T | 0.8mm +/-0.15mm |
| S | 0.58mm MIN |
| B | 0.45mm +/-0.15mm |

Packaging Specifications

| | |
|---------------------|-----------|
| Packaging: | Bulk, Bag |
| Packaging Quantity: | 1 |

General Information

| | |
|-------------------|---------------------------------|
| Series: | SMD Comm COG Flex |
| Style: | SMD Chip |
| Description: | SMD, MLCC, FT-CAP, Ultra-Stable |
| Features: | FT-CAP, Ultra-Stable |
| RoHS: | Yes |
| Termination: | Flexible Termination |
| Marking: | No |
| AEC-Q200: | No |
| Component Weight: | 4600 ug |
| Shelf Life: | 78 Weeks |
| MSL: | 1 |

Specifications

| | |
|---|---------------------------|
| Capacitance: | 680 pF |
| Measurement Condition: | 1 MHz 1.0Vrms |
| Capacitance Tolerance: | 5% |
| Voltage DC: | 250 VDC |
| Dielectric Withstanding Voltage: | 625 VDC |
| Temperature Range: | -55/+125°C |
| Temperature Coefficient: | COG |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC): | 30 ppm/C, 1MegaHz 1.0Vrms |
| Dissipation Factor: | 0.1% 1 MHz 1.0Vrms |
| Aging Rate: | 0% Loss/Decade Hour |
| Insulation Resistance: | 100 GOhms |

单击下面可查看定价，库存，交付和生命周期等信息

[>>KEMET\(基美\)](#)